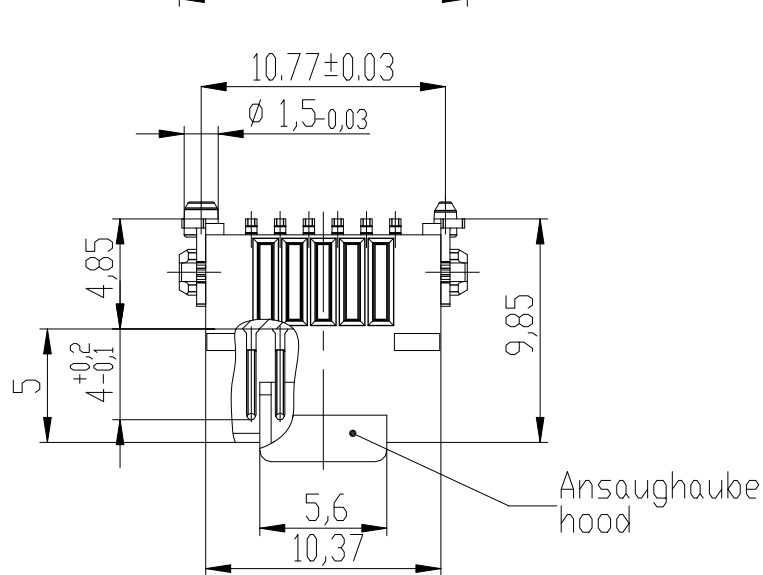
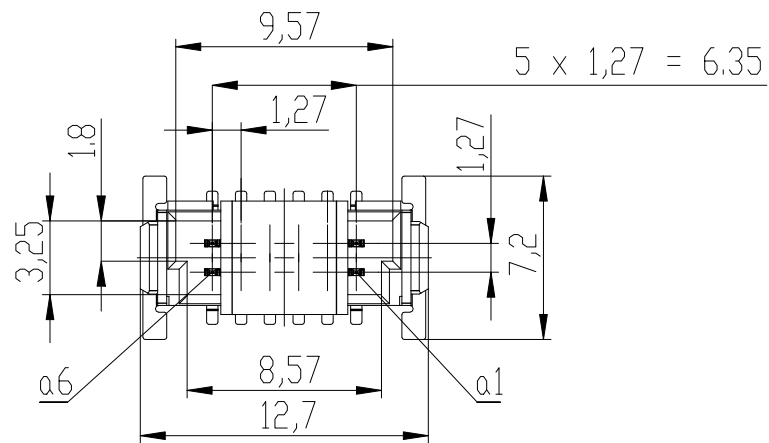
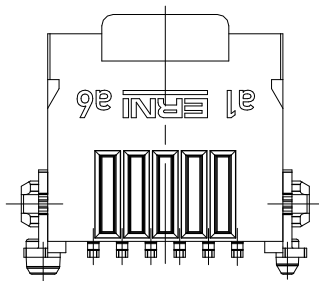


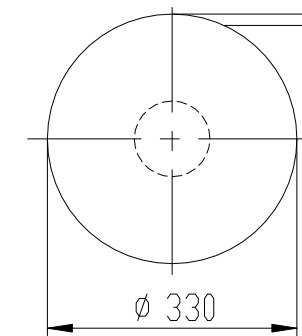
Anforderungsstufe 1
performance level 1

Kontaktbereich vergoldet
mating area gold plating

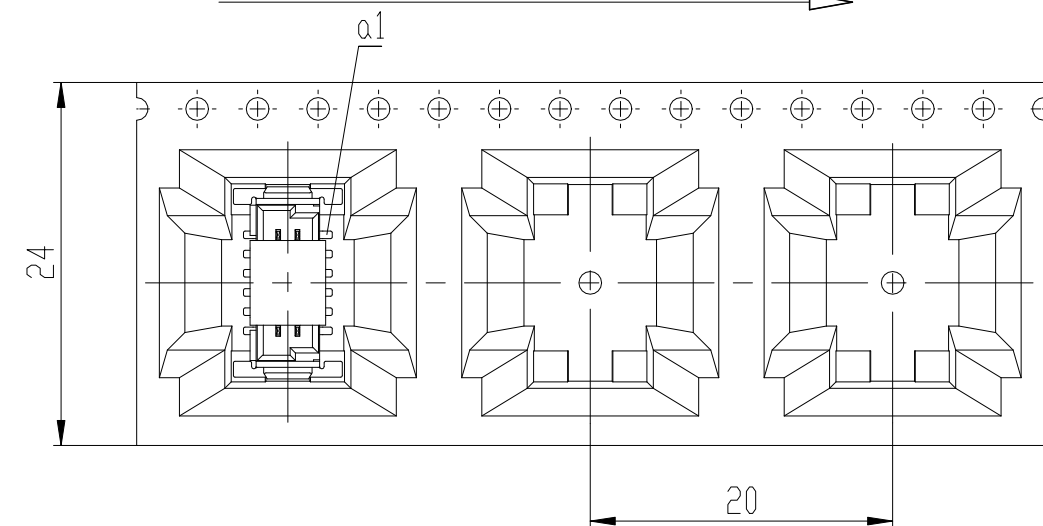
Anschlussbereich verzinkt 4-6 µm
terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
coplanarity area of termination ≤ 0,1 mm

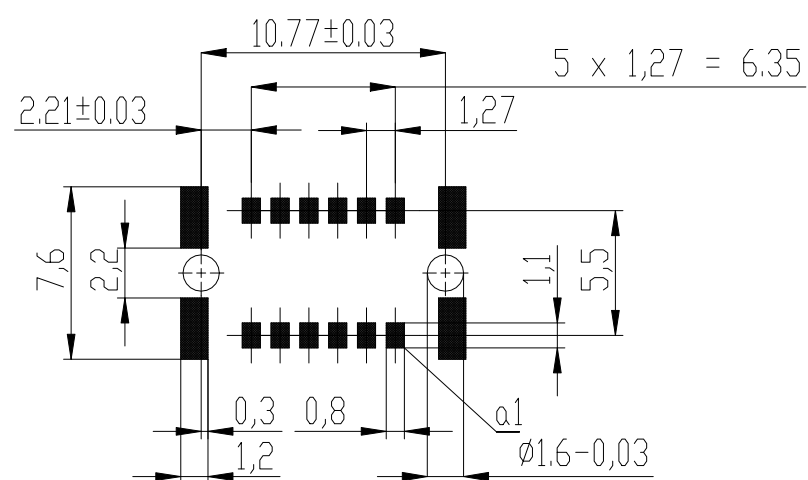
Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 250 Stück
packaging unit: 250 pcs



Abspulrichtung - Reel off Direction

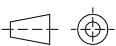


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



BA 8-23 hohe Bauhöhe
type 8-23 High Profile

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Information:		Tolerances		 All Dimensions in mm		Scale 3:1	
Customer drawing: THIS DRAWING IS A CONTROLLED DOCUMENT.		Subject to modification without prior notice. Drawing will not be updated.		Designation ERNI-Messerli, SMC-Q 12-SMD-BA8-23 Male SMC-Q 12-SMD-type8-23			
				C- 234206-E			I
f	29.10.2018			Class SMCQ			A3
Index	Date						